

ABSTRACT OF THE DISCLOSURE

This invention is a method of manufacturing a multi-layer printed wiring board including an internal layer circuit forming step, a outer layer circuit forming step, and a solder resist forming step. In the solder resist forming step, the surface of a board subjected to the outer layer circuit forming step is coated with a photosensitive solder resist material, the solder resist material is coated with a photosensitive film; a light shielding mask is formed by irradiating a laser beam on the photosensitive film according to a formed pattern of the solder resist, the solder resist material is exposed by using the light shielding mask, the light shielding mask is removed, and the solder resist material which is not exposed is removed.